



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 760 H6327	Issued	06. May 2021
MA#	MA001369468		
Package	PG-SOT343-4-2	Weight*	6.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.01		100	
	noble metal	gold	7440-57-5	0.003	0.04		389	
	inorganic material	silicon	7440-21-3	0.023	0.34	0.39	3353	3842
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.53	49.74	495510	497601
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1467	1467
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4371	
	plastics	epoxy resin	-	0.651	9.40		93981	
	inorganic material	silicondioxide	60676-86-0	2.347	33.88	43.72	338768	437120
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28756	28756
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31214	31214
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com